

## QUICKSWITCH<sup>®</sup> PRODUCTS HIGH-SPEED CMOS QUICK-SWITCH 32-BIT LOW RESISTANCE MULTIWIDTH<sup>™</sup> BUS SWITCHES

## IDTQS34XR245

## FEATURES:

- · Enhanced N channel FET with no inherent diode to Vcc
- $2.5\Omega$  bidirectional switches connect inputs to outputs
- Zero propagation delay, zero ground bounce
- QS34XR245Q3 is a 32-bit version of QS3R245
- · Flow-through pinout for easy layout
- · Undershoot clamp diodes on all switch and control inputs
- TTL-compatible control inputs
- · Available in 80-pin Millipaq package

#### **APPLICATIONS:**

- Low resistance applications
- Hot-swapping, hot-docking (low resistance for PCI and Compact PCI applications)
- · Bus switching, isolation
- · Logic replacement (data processing)
- · Capacitance reduction and isolation
- Power conservation
- Clock gating
- Voltage translation (5V to 3.3V)

## FUNCTIONAL BLOCK DIAGRAM

# 

B7

OE4

1

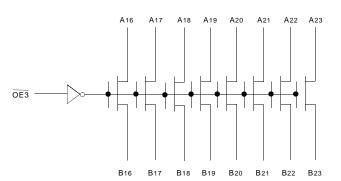
## DESCRIPTION:

The QS34XR245 is a member of the MultiWidth<sup>TM</sup> family of QuickSwitch devices and provides a set of 32 high-speed low resistance CMOS compatible bus switches in a flow-through pin out.

This device is available in the MillipaQ package, the worlds first small outline 32-bit solution. The low on-resistance of the QS34XR245 allows inputs to be connected to outputs without adding propagation delay and without generating additional ground bounce noise. When Output Enable (OEx) is low, the switches are turned on, connecting bus A to bus B. When OEx is high, the switches are turned off.

The QS34XR245 is ideally suited for 32/64 bit applications where board space is at a premium. The low resistance of QS34XR245 makes it ideal for PCI hot docking application.

QuickSwitch devices provide an order of magnitude faster speed than conventional logic devices.



A26 A27

B26 B27

B25

A 24

B24

A25

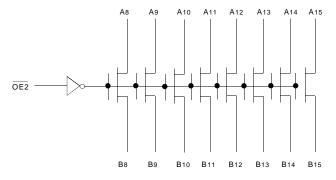
A28

B28 B29 B30

A29

A30

Δ31





B0

Β1

B2 B3

B4

B5 B6

#### INDUSTRIAL TEMPERATURE RANGE

#### NOVEMBER 1999

B31

### PINCONFIGURATION

	[		「、 ,―――	٦	
NC		1	80		Vcc
A0		2	79		OE1
A1		3	78		Bo
A2		4	77		B1
Аз		5	76		B2
A4		6	75		Вз
A5		7	74		B4
A6		8	73		B5
A7		9	72		B6
GND		10	71		B7
NC		11	70		Vcc
A8		12	69		OE2
A9		13	68		B8
A10		14	67		B9
A11		15	66		B10
A12		16	65		B11
A13		17	64		B12
A14		18	63		B13
A15		19	62		B14
GND		20	61		B15
NC		21	60		Vcc
A16		22	59		OE3
A17		23	58		B16
A18		24	57		B17
A19		25	56		B18
A20		26	55		B19
A21		27	54		B20
A22		28	53		B21
A23		29	52		B22
GND		30	51		B23
NC		31	50		Vcc
A24		32	49		OE4
A25		33	48		B24
A26		34	47		B25
A27		35	46		B26
A28		36	45		B27
A29		37	44		B28
A30		38	43		B29
A31		39	42		B30
GND		40	41		B31
		MI	LLIPAQ (Q3	)	

### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Description	Max	Unit
VTERM <sup>(2)</sup>	Supply Voltage to Ground	-0.5 to +7	V
Vterm <sup>(3)</sup>	DC Switch Voltage Vs	-0.5 to +7	V
VTERM <sup>(3)</sup>	DC Input Voltage VIN	-0.5 to +7	V
VAC	AC Input Voltage (pulse width $\leq$ 20ns)	-3	V
Ιουτ	DC Output Current	120	mA
Рмах	Maximum Power Dissipation (TA = 85°C)	1.4	W
Tstg	Storage Temperature	-65 to +150	°C

NOTE:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. Vcc terminals.

3. All terminals except Vcc.

#### CAPACITANCE

 $(TA = +25^{\circ}C, f = 1.0MHz, VIN = 0V, VOUT = 0V)$ 

Pins	Тур.	Max. <sup>(1)</sup>	Unit
Control Pins	3	4	pF
Quickswitch Channels (Switch OFF)	7	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

#### PINDESCRIPTION

Pin Names	Description		
ŌĒx	Output Enable		
Ax, Bx	Data I/Os		

#### FUNCTION TABLE<sup>(1)</sup>

OE1x	Function		
Н	Disconnect		
L	Ax = Bx		

NOTE:

1. H = HIGH Voltage Level

L = LOW Voltage Level

TOP VIEW

# DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

 ${\sf Following\,Conditions\,Apply\,Unless\,Otherwise\,Specified:}$ 

Industrial: TA =  $-40^{\circ}$ C to  $+85^{\circ}$ C, VCC =  $5.0V \pm 10\%$ 

Symbol	Parameter	Test Conditions	Min.	Typ. <sup>(1)</sup>	Max.	Unit
Vih	Input HIGH Level	Guaranteed Logic HIGH for Control Pins	2	_	_	V
Vil	Input LOW Level	Guaranteed Logic LOW for Control Pins	_	_	0.8	V
lin	Input LeakageCurrent (Control Inputs)	$0V \le VIN \le VCC$	_	—	±1	μA
loz	Off-State Output Current (Hi-Z)	$0V \le VOUT \le Vcc$ , Switches OFF	_	_	±1	μA
Ron	Switch ON Resistance <sup>(2)</sup>	VCC = Min., VIN = 0V, ION = 30mA	_	2.5	5	Ω
		VCC = Min., VIN = 2.4V, ION =15mA	—	4	8.5	
Vp	Pass Voltage <sup>(3)</sup>	$V_{IN} = V_{CC} = 5V$ , $I_{OUT} = -5\mu A$	3.7	4	4.3	V

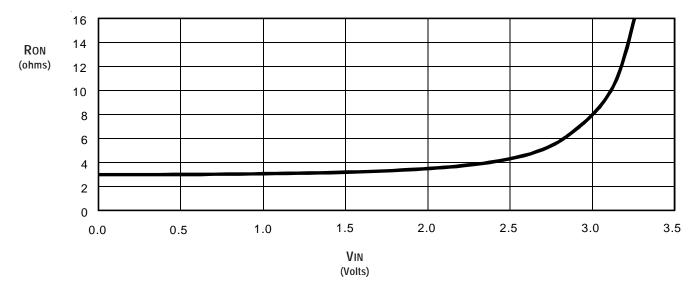
NOTES:

1. Typical values are at Vcc = 5.0V, TA = 25°C.

2. Max value of Ron is guaranteed but not production tested.

3. Pass Voltage is guaranteed but not production tested.

## TYPICAL ON RESISTANCE vs VIN AT Vcc = 5V



## POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions <sup>(1)</sup>	Max.	Unit
lcca	Quiescent Power Supply Current	Vcc = Max., VIN = GND or Vcc, f = 0	12	μΑ
Δlcc	Power Supply Current per Control Input HIGH <sup>(2)</sup>	Vcc = Max., VIN = 3.4V, f = 0	2.5	mA
ICCD	Dynamic Power Supply Current per MHz <sup>(3)</sup>	Vcc = Max., A and B pins open Control Inputs Toggling at 50% Duty Cycle	0.25	mA/MHz

NOTES:

1. For conditions shown as Min. or Max., use the appropriate values specified under DC Electrical Characteristics.

2. Per TLL driven input (VIN = 3.4V, control inputs only). A and B pins do not contribute to  $\Delta$ Icc.

3. This current applies to the control inputs only and represents the current required to switch internal capacitance at the specified frequency. The A and B inputs generate no significant AC or DC currents as they transition. This parameter is guaranteed but not production tested.

# SWITCHING CHARACTERISTICS OVER OPERATING RANGE

 $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ ,  $V_{CC} = 5.0V \pm 10\%$ ;

CLOAD = 50pF, RLOAD = 500 $\Omega$  unless otherwise noted.

Symbol	Parameter	Min. <sup>(1)</sup>	Тур.	Max.	Unit
<b>t</b> PLH	Data Propagation Delay <sup>(2,3)</sup>	—	—	0.12	ns
<b>t</b> PHL	Ax to/from Bx				
tPZL	Switch Turn-on Delay	0.5	—	5.6	ns
tрzн	OE to Ax/Bx				
tPLZ	Switch Turn-off Delay <sup>(2)</sup>	0.5	—	4.5	ns
tphz	OE to Ax/Bx				

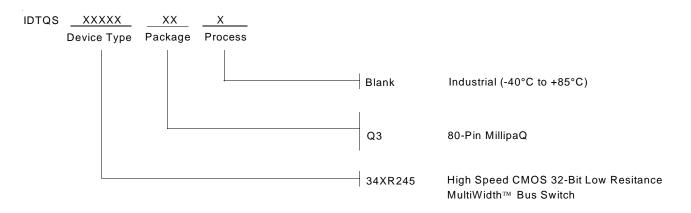
NOTES:

1. Minimums are guaranteed but not production tested.

2. This parameter is guaranteed but not production tested.

<sup>3.</sup> The bus switch contributes no propagation delay other than the RC delay of the ON resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.12ns for CL = 30pF. Since this time constant is much smaller than the rise and fall times of typical driving signals, it adds very little propagation delay to the system. Propagation delay of the bus switch, when used in a system, is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.

## ORDERING INFORMATION





*CORPORATE HEADQUARTERS* 2975 Stender Way Santa Clara, CA 95054 *for SALES:* 800-345-7015 or 408-727-6116 fax: 408-492-8674 www.idt.com *for Tech Support:* logichelp@idt.com (408) 654-6459